

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE30ND35Q uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =30V,I_D =35A

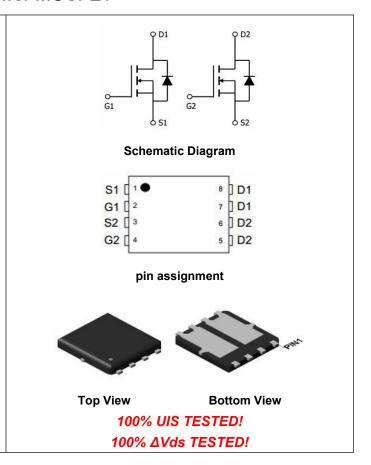
 $R_{DS(ON)}$ <13m Ω @ V_{GS} =10V

 $R_{\text{DS(ON)}}$ <23m Ω @ V_{GS} =4.5V

- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE30ND35Q	NCE30ND35Q	PDFN3.3X3.3-8L	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage	V _G s	±20	V	
Drain Current-Continuous	I _D	35	А	
Drain Current-Continuous(T _C =100 °C)	I _D (100°C)	24.8	А	
Pulsed Drain Current	I _{DM}	140	А	
Maximum Power Dissipation	P _D	30	W	
Derating factor		0.24	W/℃	
Single pulse avalanche energy (Note 5)	E _{AS}	72	mJ	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$	

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{eJC}	4.17	°C/W



Electrical Characteristics (T_c=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	•					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1.0	1.6	2.2	V
Dunin Course On State Besistance	В	V _{GS} =10V, I _D =20A	-	11	13	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =20A	-	17	23	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =20A	26	-	-	S
Dynamic Characteristics (Note4)	•		•			
Input Capacitance	C _{lss}	V _{DS} =15V,V _{GS} =0V, F=1.0MHz	800	1000	1500	PF
Output Capacitance	Coss		-	180.8	-	PF
Reverse Transfer Capacitance	C _{rss}	F-1.UIVIDZ	-	164.4	-	PF
Switching Characteristics (Note 4)	•		•			
Turn-on Delay Time	t _{d(on)}		-	5	-	nS
Turn-on Rise Time	t _r	V _{DD} =15V, R _L =0.75Ω	-	12	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{G} =3 Ω	-	19	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg	\/ 45\/1 00A	-	17		nC
Gate-Source Charge	Qgs	V _{DS} =15V,I _D =20A, V _{GS} =10V	-	2.8		nC
Gate-Drain Charge	Q _{gd}		-	3.9		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	35	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, I _F =20A	-	19	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	10	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negl	igible (turi	n-on is do	minated b	y LS+LD)

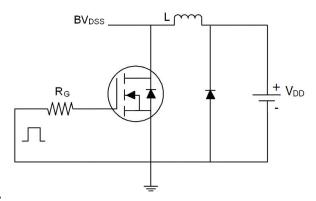
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production

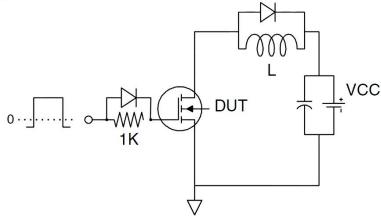


Test circuit

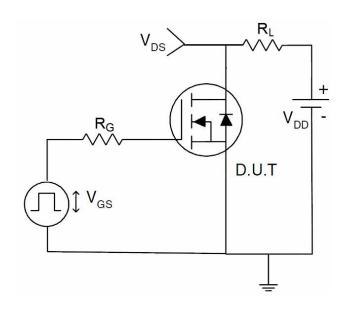
1) Eas test Circuits



2) Gate charge test Circuit:



3) Switch Time Test Circuit:





Typical Electrical and Thermal Characteristics (Curves)

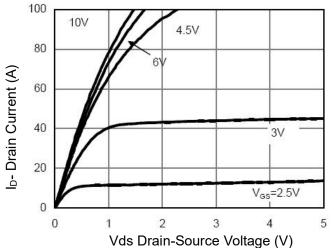


Figure 1 Output Characteristics

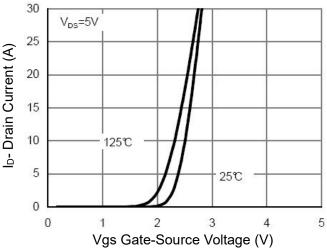


Figure 2 Transfer Characteristics

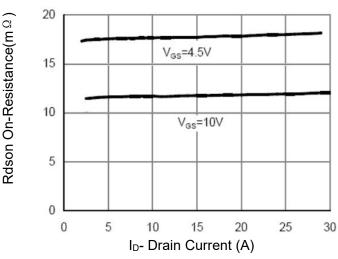


Figure 3 Rdson- Drain Current

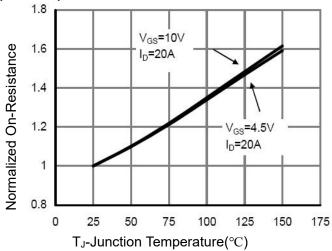


Figure 4 Rdson-Junction Temperature

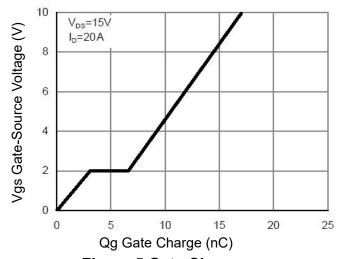


Figure 5 Gate Charge

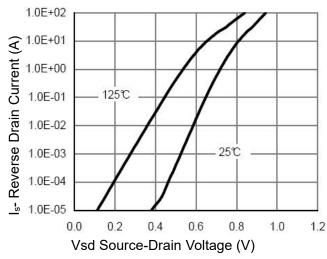
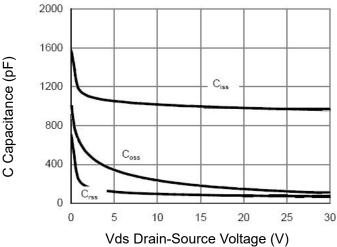


Figure 6 Source- Drain Diode Forward





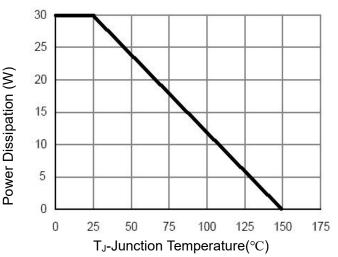
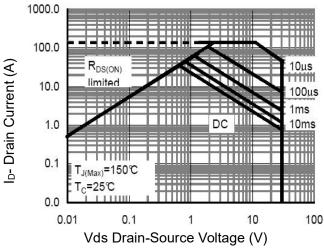


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating



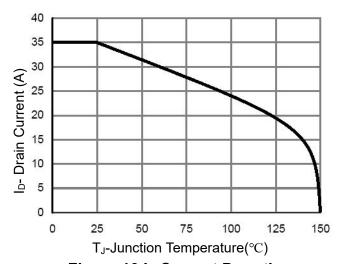


Figure 8 Safe Operation Area

Figure 10 ID Current De-rating

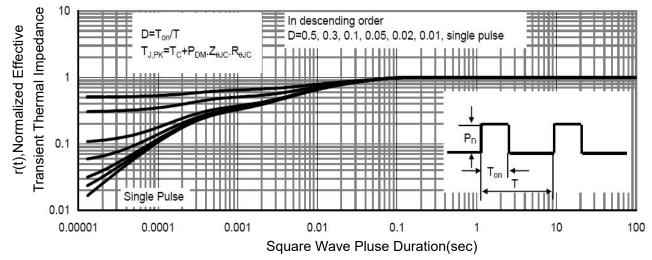
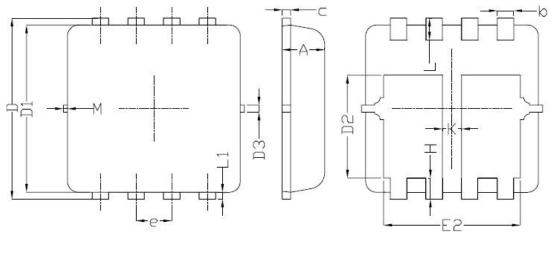
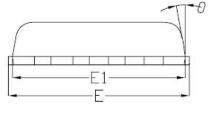


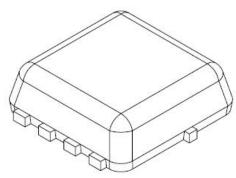
Figure 11 Normalized Maximum Transient Thermal Impedance



DFN3.3X3.3-8L Package Information



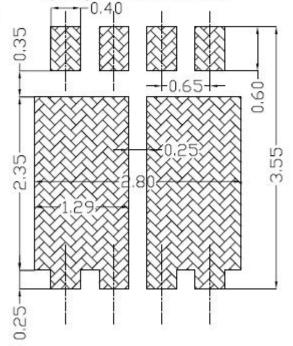




Land Pattern

(Only for Reference)

SYMBOL	DIMENSIONAL REQMTS			
	MIN	NOM	MAX	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
c	0.10	0.15	0.25	
D	3.25	3.35	3.45	
DI	3.00	3.10	3.20	
D2	1.78	1.88	1.98	
D3		0.13		
E	3.20	3.30	3.40	
El	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
e		0.65BSC	ì	
H	0.30	0.39	0.50	
L	0.30	0.40	0.50	
LI		0.13		
K	0.30			
θ	222	10°	12°	
M	*	*	0.15	





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